



## 20V Dual P-Channel MOSFETs

### General Description

The S9MPB016 is the Dual P-Channel logic enhancement mode power field effect transistor is produced using high cell density, DMOS trench technology.

This high-density process is especially tailored to minimize on-state resistance.

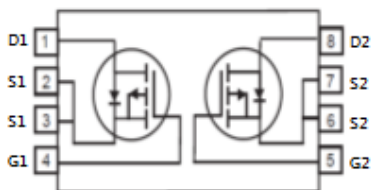
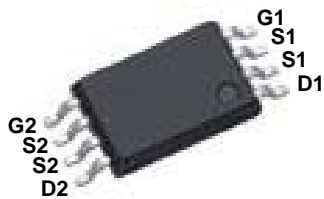
These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other Battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
-20 V	16 m $\Omega$	-11 A

### Features

- -20V, -11A,  $R_{DS(ON)}=16m\Omega @V_{GS}=-4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

TSSOP-8 Pin Configuration



### Applications

- POWER Management in Note
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC

### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current - Continuous ( $T_A=25^\circ\text{C}$ )	-11	A
	Drain Current - Continuous ( $T_A=100^\circ\text{C}$ )	-7	A
$I_{DM}$	Drain Current - Pulsed	-44	A
$P_D$	Power Dissipation	1.25	W
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
Marking Code		PB016	

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	100	$^\circ\text{C/W}$

**20V Dual P-Channel MOSFETs****Electrical Characteristics (T<sub>A</sub>=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V , I <sub>D</sub> = -250uA	-20	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> = -20V , V <sub>GS</sub> = 0V	---	---	-1	uA
		V <sub>DS</sub> = -16V , V <sub>GS</sub> = 0V , T <sub>J</sub> =125°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±12V , V <sub>DS</sub> = 0V	---	---	±100	nA

**On Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -4.5V , I <sub>D</sub> = -6A	---	12	16	mΩ
		V <sub>GS</sub> = -2.5V , I <sub>D</sub> = -4A	---	16	22	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> = -250uA	-0.3	-0.6	-1	V

**Dynamic and switching Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -10V , V <sub>GS</sub> = -4.5V , I <sub>D</sub> = -6A	---	27	40	nC
Q <sub>gs</sub>	Gate-Source Charge		---	2.4	4.8	
Q <sub>gd</sub>	Gate-Drain Charge		---	5.3	8	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> = -10V , V <sub>GEN</sub> = -4.5V , R <sub>G</sub> = 25Ω , I <sub>D</sub> = -1A	---	16.2	31	nS
T <sub>r</sub>	Rise Time		---	43.5	83	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	114	217	
T <sub>f</sub>	Fall Time		---	28.8	55	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V , V <sub>GS</sub> = 0V , F= 1MHz	---	2320	3370	pF
C <sub>oss</sub>	Output Capacitance		---	280	410	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	175	260	

**Drain-Source Diode Characteristics and Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> = 0V , I <sub>S</sub> = -1A	---	---	-1	V



Characteristics Curves

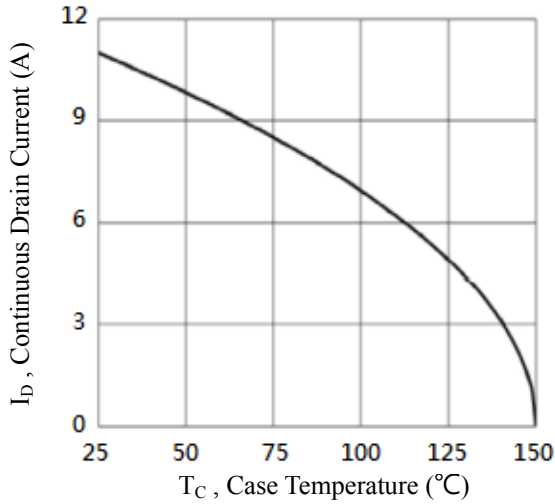


Fig.1 Continuous Drain Current vs.  $T_c$

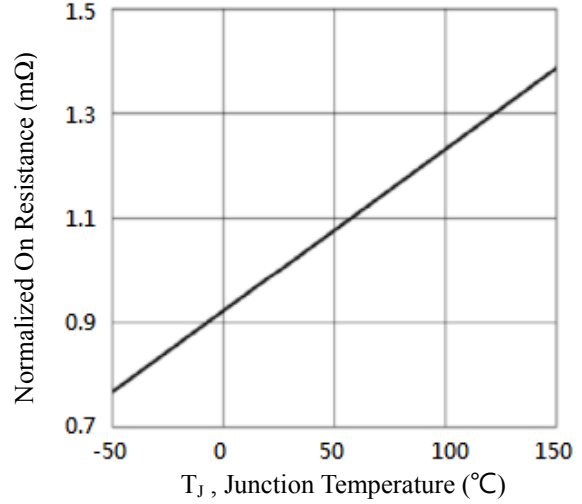


Fig.2 Normalized RDSON vs.  $T_j$

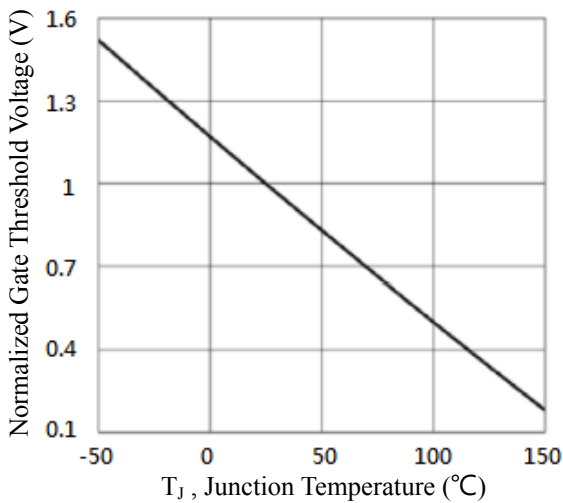


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

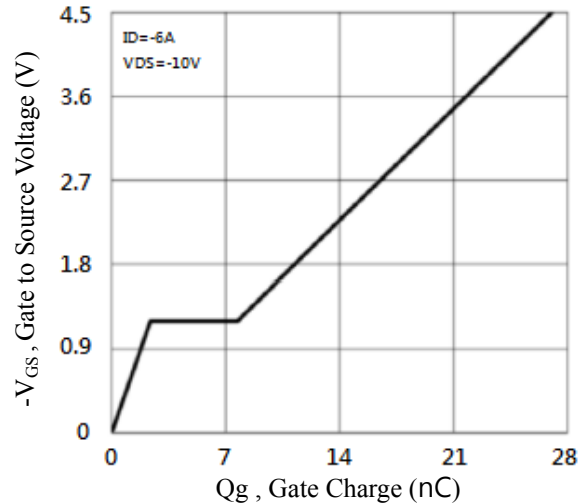


Fig.4 Gate Charge Waveform

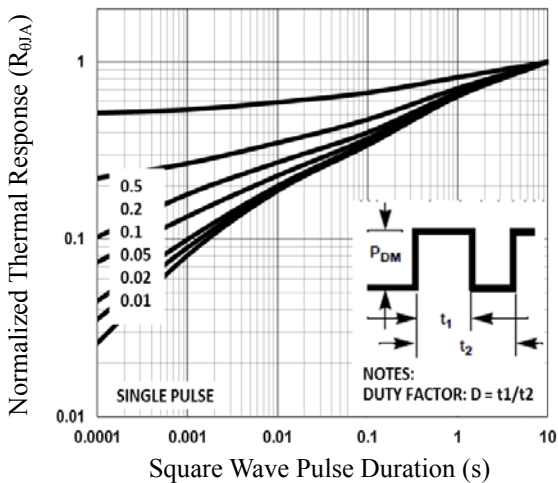


Fig.5 Normalized Transient Response

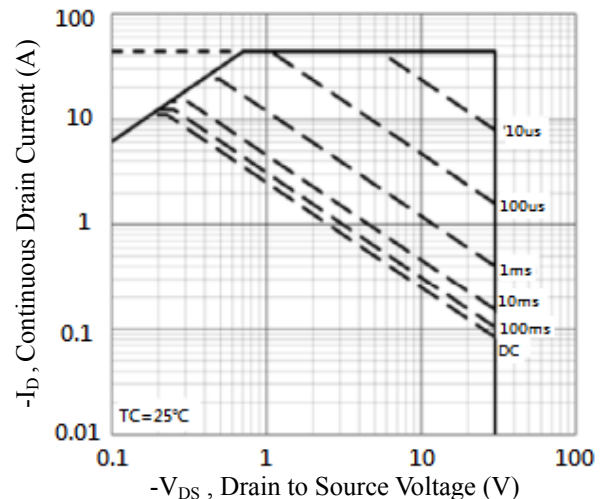


Fig.6 Maximum Safe Operation Area



Characteristics Curves

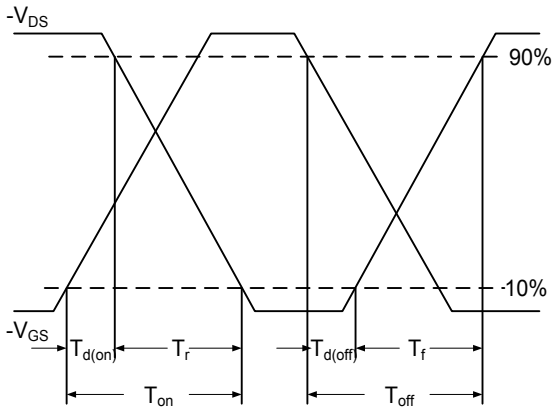


Fig.7 Switching Time Waveform

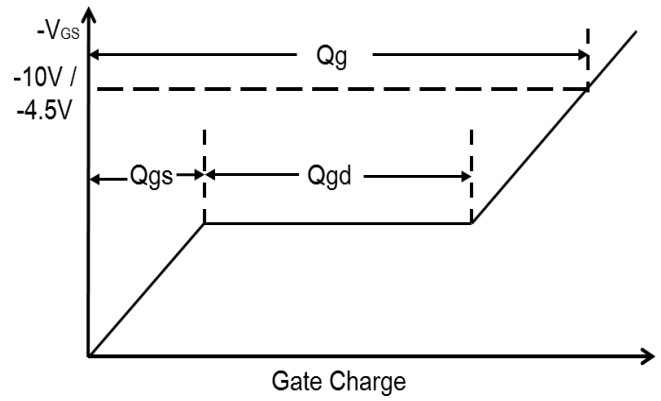
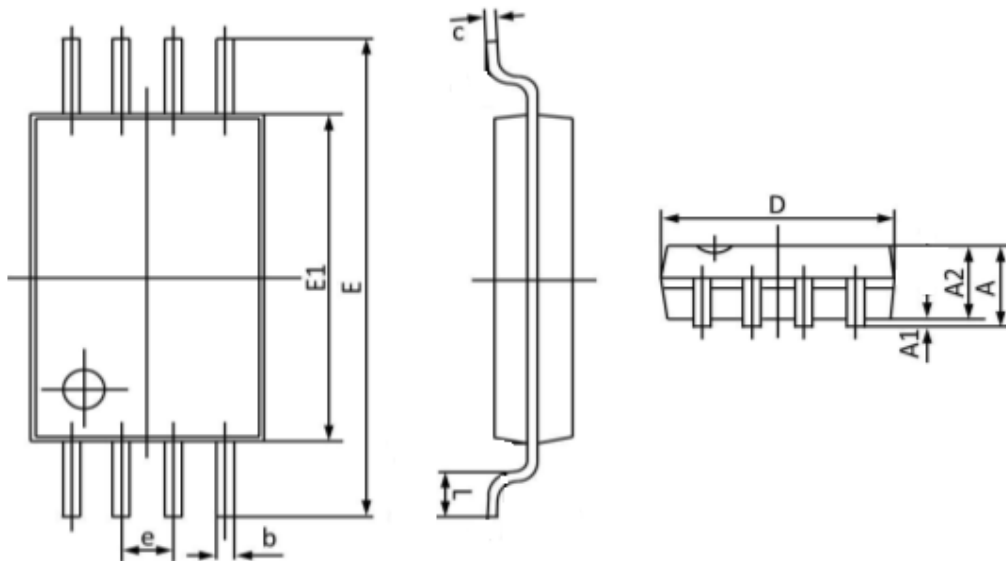


Fig.8 Gate Charge Waveform



Package Outline Dimensions

TSSOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	-	1.200	-	0.047
A1	0.020	0.150	0.001	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.011
c	0.090	0.200	0.004	0.008
D	2.900	3.100	0.114	0.122
E	6.200	6.600	0.244	0.260
E1	4.300	4.500	0.169	0.177
e	0.650(BSC)		0.025(BSC)	
L	0.450	0.750	0.018	0.029



## LEGAL DISCLAIMER

- The product is provided “AS IS” without any guarantees or warranty. In association with the product, Eris Technology Corporation, its affiliates, and their directors, officers, employees, agents, successors and assigns (collectively, the “Eris”) makes no warranties of any kind, either express or implied, including but not limited to warranties of merchantability, fitness for a particular purpose, of title, or of non-infringement of third party rights.
- The information in this document and any product described herein are subject to change without notice and should not be construed as a commitment by Eris. Eris assumes no responsibility for any errors that may appear in this document.
- Eris does not assume any liability arising out of the application or use of this document or any product described herein, any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Eris and all the companies whose products are represented on Eris website, harmless against all damages.
- No license, express or implied, by estoppels or otherwise, to any intellectual property is granted by this document or by any conduct of Eris. Product name and markings notes herein may be trademarks of their respective owners.
- Eris does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- Should Customers purchase or use Eris products for any unintended or unauthorized application, Customers shall indemnify and hold Eris and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.
- The official text is written in English and the English version of this document is the only version endorsed by Eris. Any discrepancies or differences created in the translations are not binding and have no legal effect on Eris for compliance or enforcement purposes.